

SOT594-1

Ceramic window quad chip carrier; no leads; 32 terminals; body 10.67 x 10.67 x 2.23 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	CWQCCN32
Package type industry code	CWQCCN32
Package style descriptive code	CWQCCN (ceramic window quad chip carrier; no leads)
Package style suffix code	NA (not applicable)
Package body material type	C (ceramic)
JEDEC package outline code	MS-009
Mounting method type	S (surface mount)
Issue date	12-3-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		10.54	-	10.67	10.92	mm
E	package width		10.54	-	10.67	10.92	mm
A	seated height		2	-	2.23	2.5	mm
A ₂	package height		1.45	-	1.65	1.85	mm
n ₂	actual quantity of termination		-	-	32	-	



Ceramic window quad chip carrier; no leads; 32 terminals;
terminals;body 10.67 x 10.67 x 2.23 mm

2. Package outline

CWQCCN32: ceramic window quad chip carrier; no leads; 32 terminals;
body 10.67 x 10.67 x 2.23 mm

SOT594-1

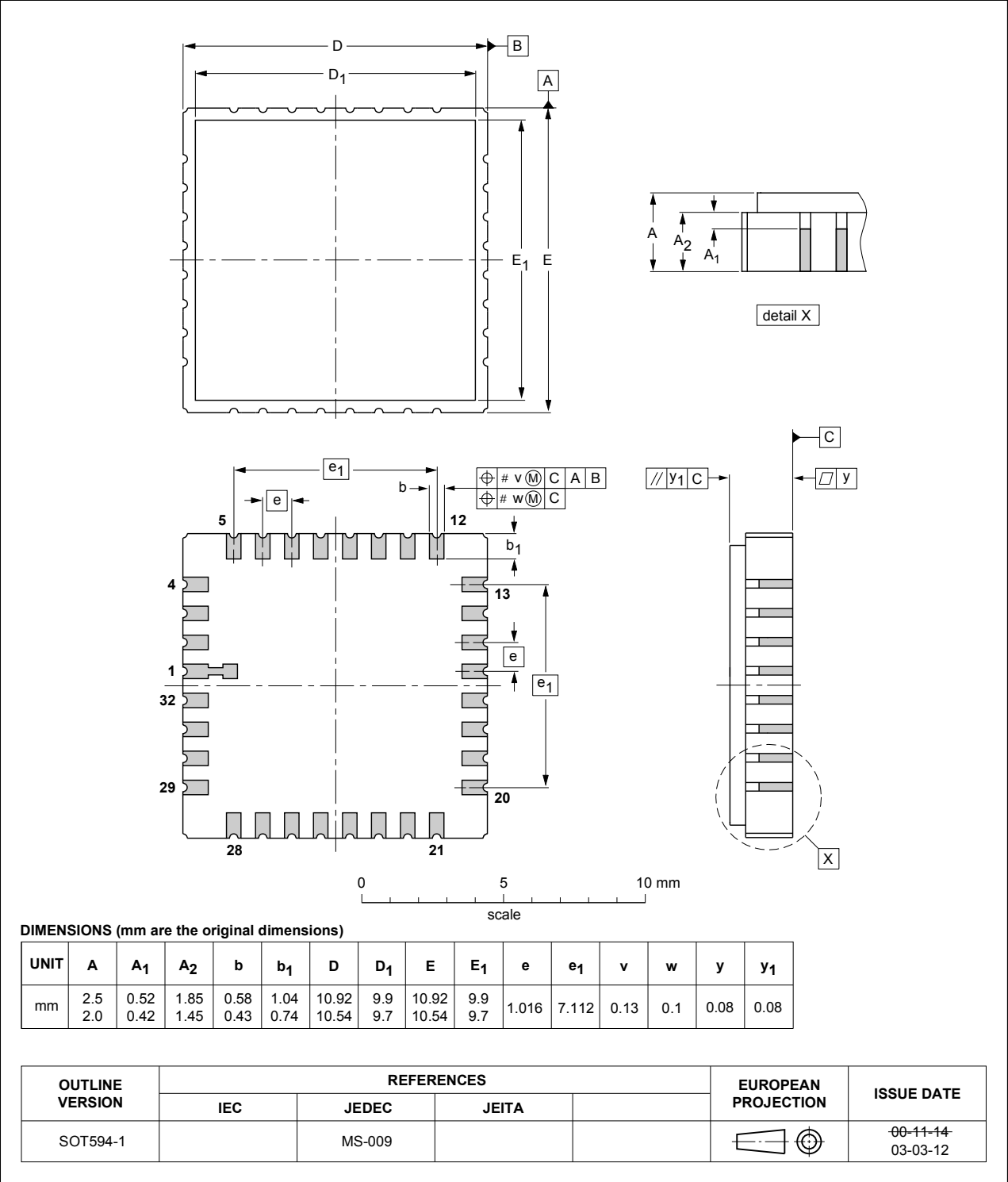


Fig. 1. Package outline CWQCCN32 (SOT594-1)

Ceramic window quad chip carrier; no leads; 32
terminals; body 10.67 x 10.67 x 2.23 mm

3. Legal information

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